

Sheet 1 of 1

Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 10559-855001	Application No.
Information Disclosure Statement by Applicant (Use several sheets if necessary) (37 CFR §1.98(b))		Applicant Valery M. Dubin	
		Filing Date September 24, 2003	Group Art Unit

U.S. Patent Documents							
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
<i>bwb</i>	AA	6,325,909	12/04/2001	Li et al.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

Foreign Patent Documents or Published Foreign Patent Applications								
Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							

Other Documents (include Author, Title, Date, and Place of Publication)		
Examiner Initial	Desig. ID	Document
<i>bwb</i>	AQ	Frank G. Shi, "Advanced IC Interconnect and Packaging: Materials and Processing Issues", Project Report 2000-01 for MICRO Project 00-088
<i>↓</i>	AR	Jamin Ling et al., "Direct Bump-on-Copper Process for Flip Chip Technologies", Kulicke & Soffa - Flip Chip Division, Agere Systems Inc.
<i>↓</i>	AS	R. Martel et al., "Carbon Nanotube Field-Effect Transistors and Logic Circuits", 2000 ACM 1-58113-461-4/02/0006
	AT	

Examiner Signature <i>[Signature]</i>	Date Considered 10/14/04
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

Substitute Disclosure Form (PTO-1449)

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